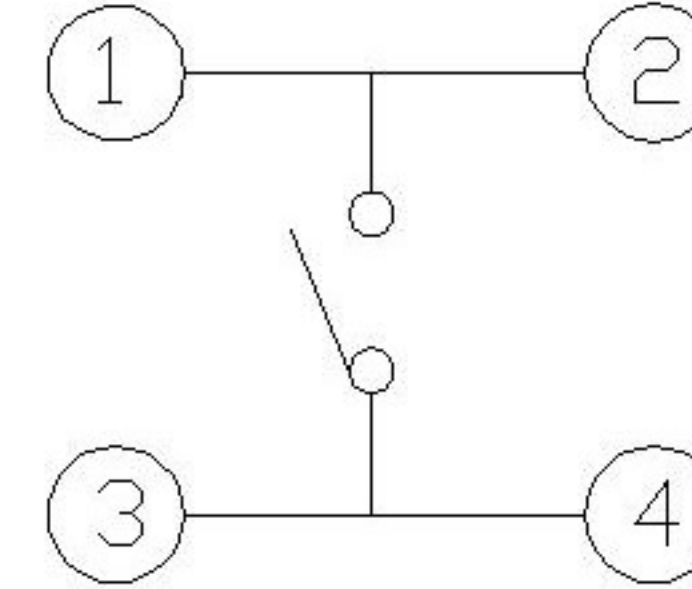
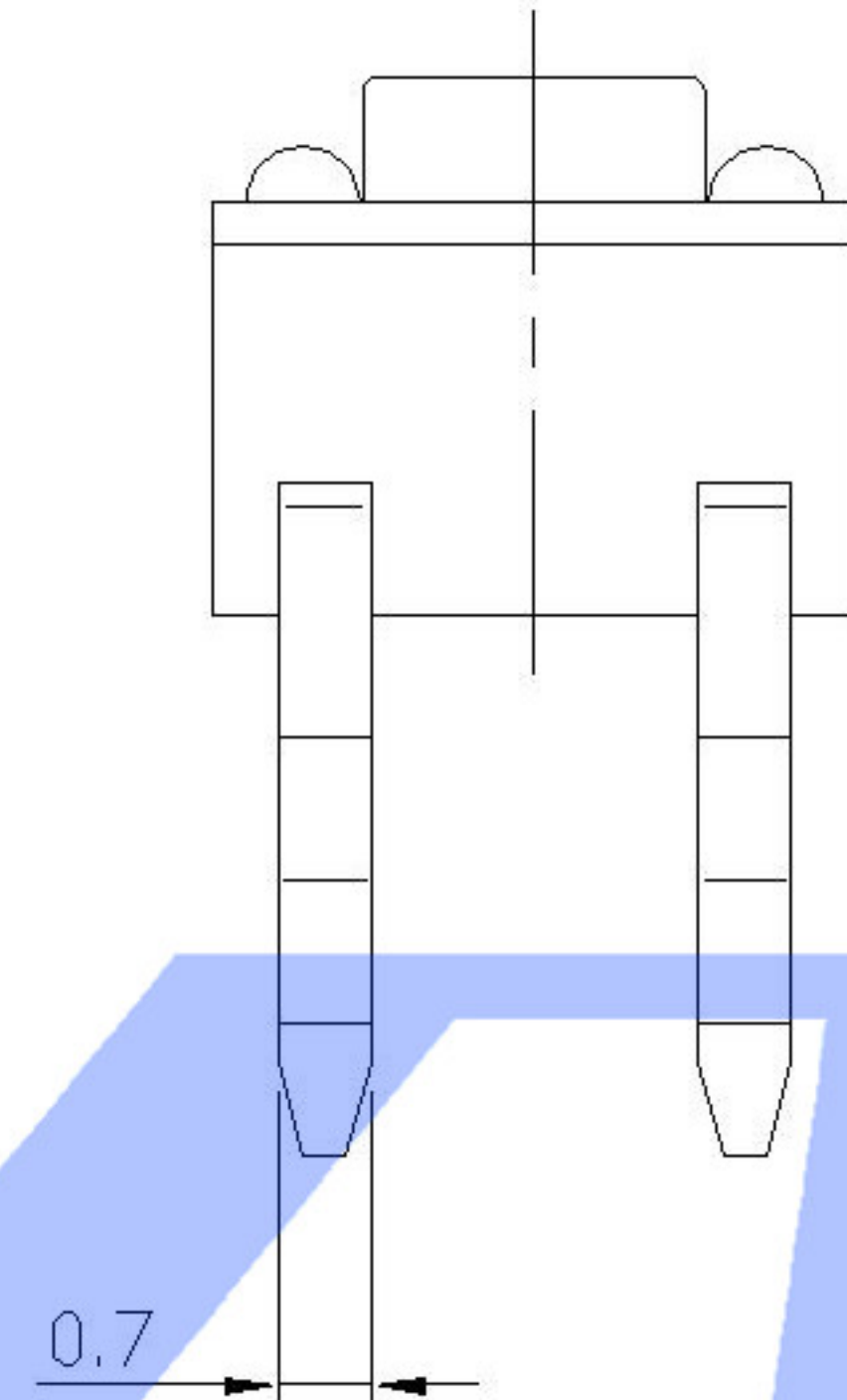
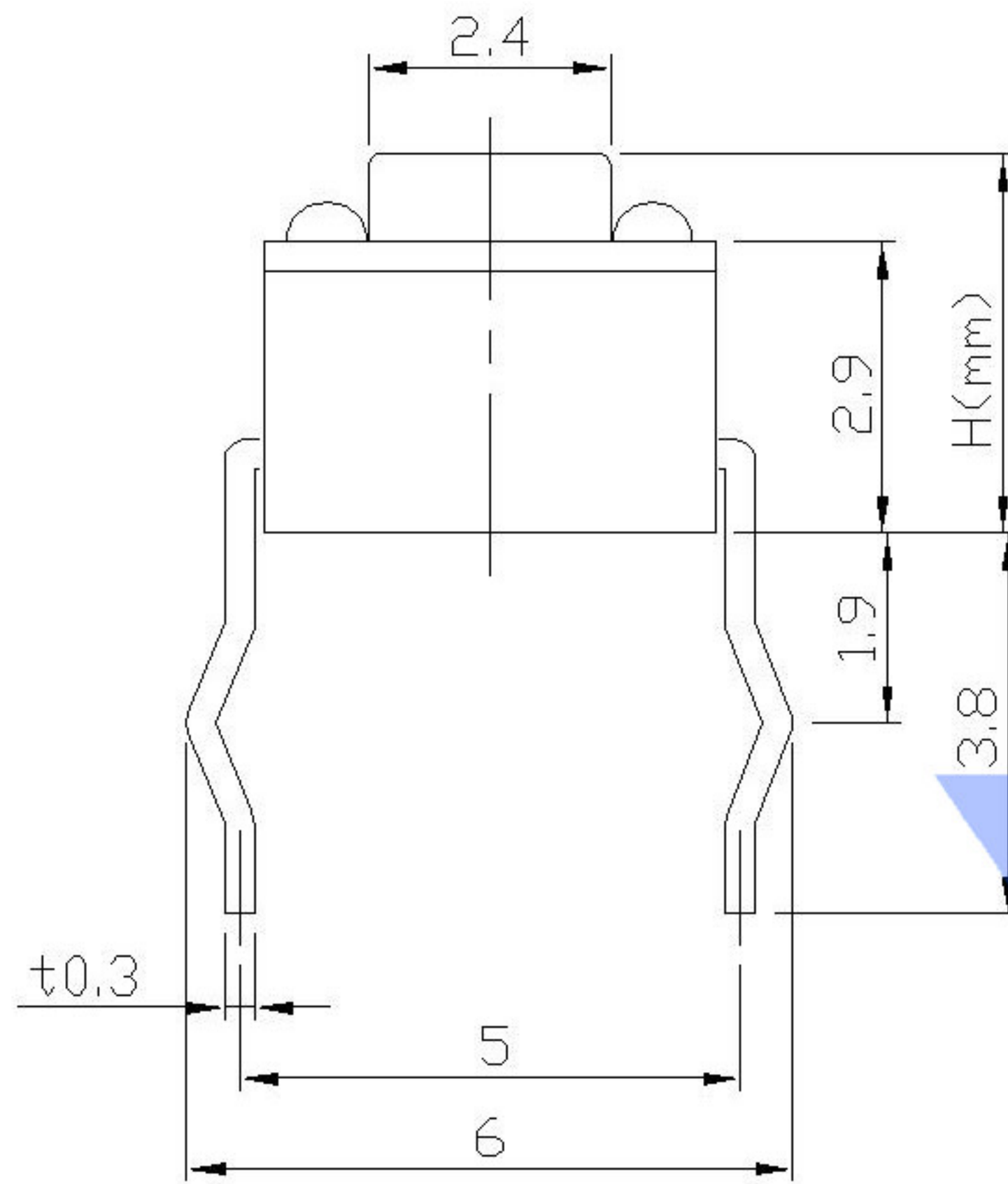
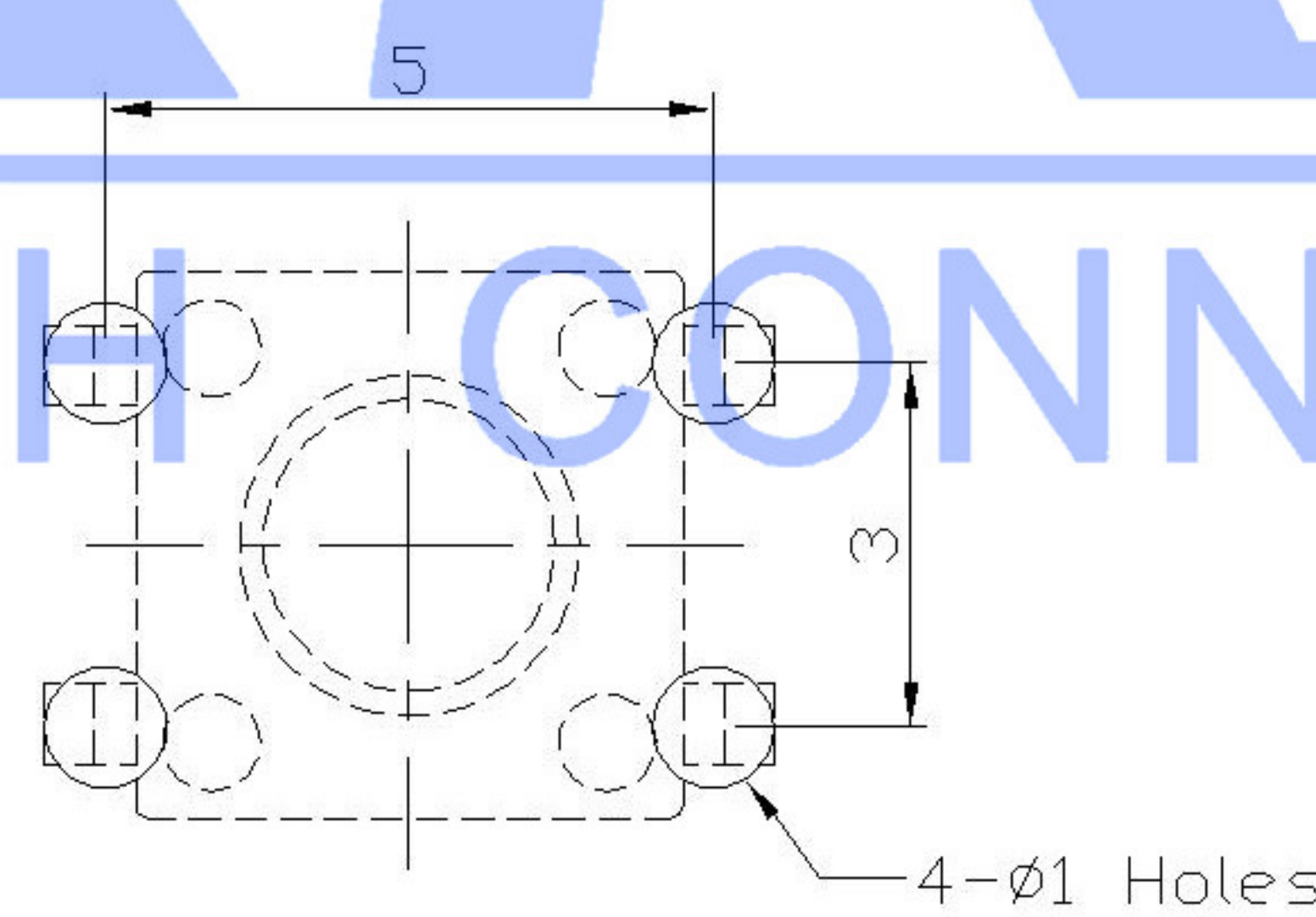
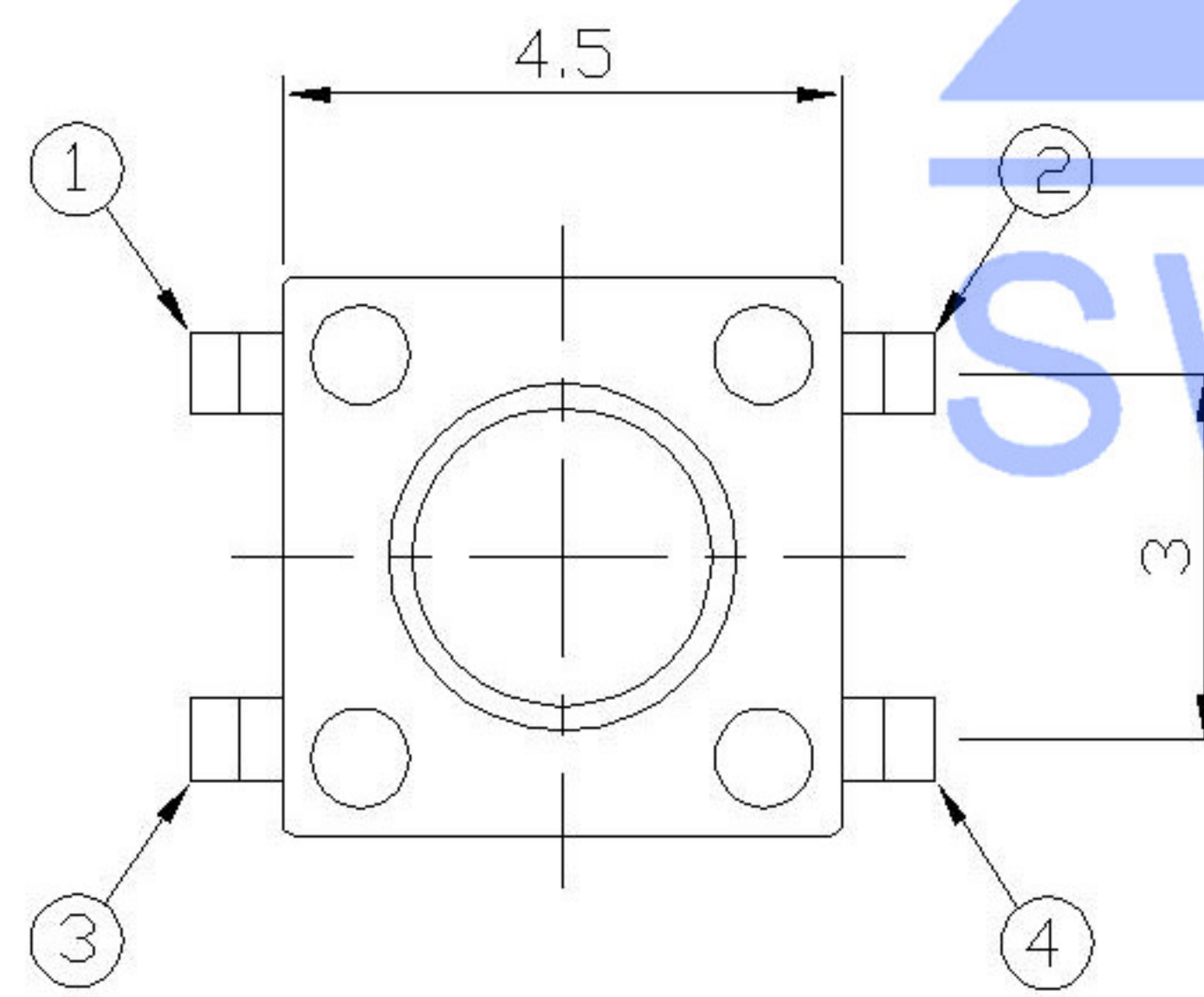


CIRCUIT DIAGRAM



Code-X	H
A	3.8
B	4.3
C	4.5
D	5.0
E	5.5
F	6.0
G	6.5
H	7.0
I	7.5
J	8.0
K	8.5
L	9.0

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating 50mA 12V DC
Contact Resistance 100mΩ max.
Insulation Resistance 100MΩ min. 500V DC
Dielectric Strength 250V AC/1 minute
Travel 0.25mm
Operating Temp. -25°C ~ +70°C
Storage Temp. -30°C ~ +80°C

PAPT NO	TC-1109-X-X
Operating Force	A: 100gf B: 160gf C: 260gf
Height	Code-X

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	---	4	Brass (0.30t)	ag Plated	---
④	Contact	---	1	F.ag/SUS	---	---
③	Base	---	1	PA46	---	---
②	Cover	---	1	Brass	Tin plated	---
①	Keystake	---	1	PA46	---	---

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: TACT SWITCH	
Δ X					units: mm	DWN	DATE	VIEW:	PART NO.:	
Δ X					tolerance:	CHKD	DATE	UNIT: mm	DWG NO.:	
Δ X					X.X ±0.2mm	APPD	DATE	SIZE: A4	TC-1109-X-X	
MARK					X.XX ±0.1mm	XKB INDUSTRIAL PRECISION CO.,LIMITED			WEIGHT	
					X.XXX ±0.05mm				1.0g	SHEET
REVISIONS									1/1	A0